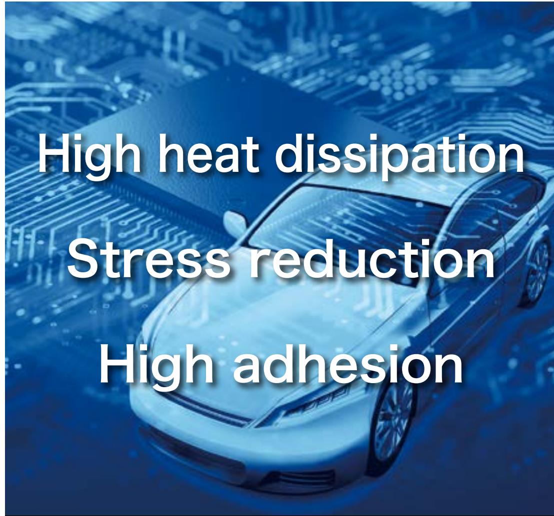
Panasonic INDUSTRY



Applications

IC Package/Automotive

Automotive module, Inverter module for major appliances and industrial motors

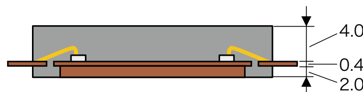
LEXCM CF

CV4180 CV4380

For power modules high thermal conductive semiconductor encapsulation materials

Achieving high mountability and high heat dissipation (Package warpage control). Suitable for large packages with heat spreaders exposed (T/C resistance improvement due to stress reduction). Compatible with nickel plating (Achieved high adhesion).

Stress reduction: Thermal cycle (T/C) resistance

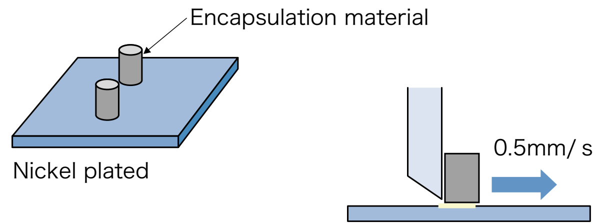


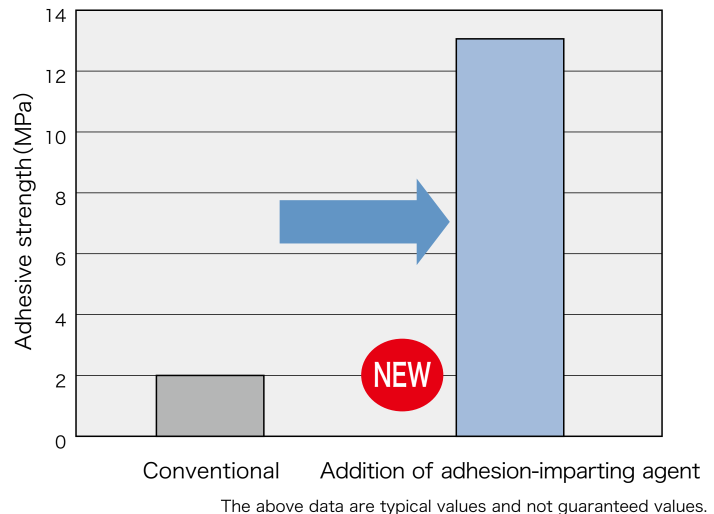
Mold size : 44x65x6.4mmt
Die size : 40x50x0.4mmt
Cu plate size : 36x46x2.0mmt

SAT image after TC -50℃ (30 min) ⇔ +150℃ (30min)

	After cure	100 cycles	300 cycles	500 cycles
Ref E=20GPa				
New E=14GPa				

Nickel plating adhesion: Shear adhesive strength





The above data are typical values and not guaranteed values.

Line-up

Part Number	Applications	Features
CV3300 / CV4380	Encapsulation of fully-molded module	High thermal conductive grade (1.7-2.3 W/mK)
CV4500 / CV4580		Super high thermal conductive grade (3.0-3.5 W/mK)
CV4100A / CV4180A	Encapsulation of module with heat spreader exposed	Low stress type for metallic substrates
CV4100B / CV4180B		Low stress type for ceramic substrates

Please see our website for Notes before you use.

industrial.panasonic.com/ww/electronic-materials

Panasonic Industry CV4180

Panasonic Industry Co., Ltd. Electronic Materials Business Division

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